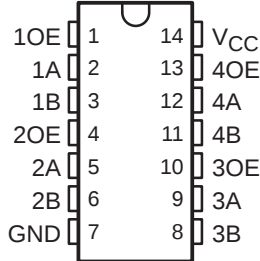


SN74CBTLV3126 LOW-VOLTAGE QUADRUPLE FET BUS SWITCH

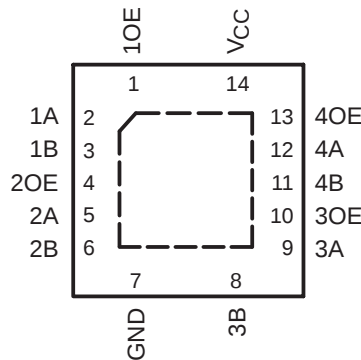
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- Standard '126-Type Pinout
- 5- Ω Switch Connection Between Two Ports
- Rail-to-Rail Switching on Data I/O Ports
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-up Performance Exceeds 100 mA per JESD 78, Class II

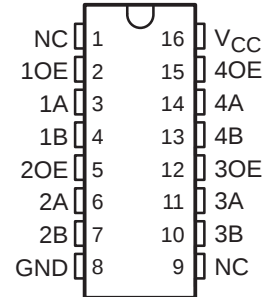
D, DGV, OR PW PACKAGE
(TOP VIEW)



RGY PACKAGE
(TOP VIEW)



DBQ PACKAGE
(TOP VIEW)



NC – No internal connection

description/ordering information

The SN74CBTLV3126 quadruple FET bus switch features independent line switches. Each switch is disabled when the associated output-enable (OE) input is low.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} feature ensures that damaging current will not backflow through the device when it is powered down. The device has isolation during power off.

To ensure the high-impedance state during power up or power down, OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

T _A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QFN – RGY	Tape and reel	SN74CBTLV3126RGYR	CL126
	SOIC – D	Tube	SN74CBTLV3126D	CBTLV3126
		Tape and reel	SN74CBTLV3126DR	
	SSOP (QSOP) – DBQ	Tape and reel	SN74CBTLV3126DBQR	CL126
	TSSOP – PW	Tape and reel	SN74CBTLV3126PWR	CL126
	TVSOP – DGV	Tape and reel	SN74CBTLV3126DGV	CL126

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE
(each bus switch)

INPUT OE	FUNCTION
L	Disconnect
H	A port = B port



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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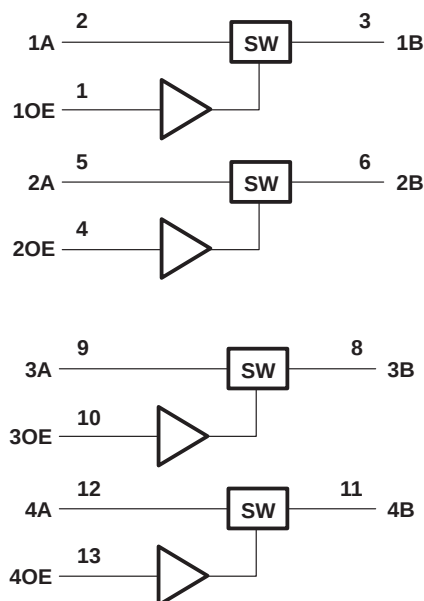
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SN74CBTLV3126

LOW-VOLTAGE QUADRUPLE FET BUS SWITCH

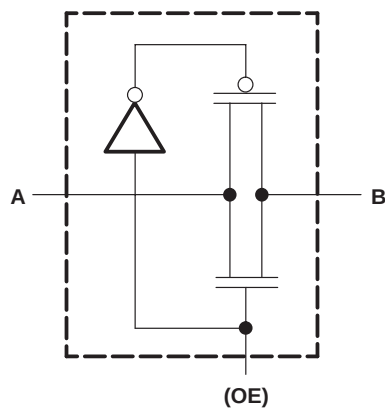
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logic diagram (positive logic)



Pin numbers shown are for the D, DGV, PW, and RGY packages.

simplified schematic, each FET switch



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 4.6 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	86°C/W
(see Note 2): DBQ package	90°C/W
(see Note 2): DGV package	127°C/W
(see Note 2): PW package	113°C/W
(see Note 3): RGY package	47°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 2. The package thermal impedance is calculated in accordance with JESD 51-7.
 3. The package thermal impedance is calculated in accordance with JESD 51-5.

recommended operating conditions (see Note 4)

		MIN	MAX	UNIT
V_{CC}	Supply voltage	2.3	3.6	V
V_{IH}	High-level control input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$ 1.7		V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$ 2		
V_{IL}	Low-level control input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$ 0.7		V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$ 0.8		
T_A	Operating free-air temperature	–40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [‡]	MAX	UNIT
V_{IK}	$V_{CC} = 3 \text{ V}$, $I_I = -18 \text{ mA}$			–1.2	V
I_I	$V_{CC} = 3.6 \text{ V}$, $V_I = V_{CC}$ or GND			±1	μA
I_{off}	$V_{CC} = 0$, V_I or $V_O = 0$ to 3.6 V			10	μA
I_{CC}	$V_{CC} = 3.6 \text{ V}$, $I_O = 0$, $V_I = V_{CC}$ or GND			10	μA
$\Delta I_{CC}^{\S}$	Control inputs $V_{CC} = 3.6 \text{ V}$, One input at 3 V, Other inputs at V_{CC} or GND			300	μA
C_i	Control inputs $V_I = 3 \text{ V}$ or 0			2.5	pF
$C_{io(OFF)}$	$V_O = 3 \text{ V}$ or 0, OE = GND			7	pF
$r_{on}^{\parallel}$	$V_{CC} = 2.3 \text{ V}$, TYP at $V_{CC} = 2.5 \text{ V}$	$V_I = 0$	$I_I = 64 \text{ mA}$	5	Ω
			$I_I = 24 \text{ mA}$	5	
		$V_I = 1.7 \text{ V}$	$I_I = 15 \text{ mA}$	27	
	$V_{CC} = 3 \text{ V}$	$V_I = 0$	$I_I = 64 \text{ mA}$	5	
			$I_I = 24 \text{ mA}$	5	
		$V_I = 2.4 \text{ V}$	$I_I = 15 \text{ mA}$	10	

[‡] All typical values are at $V_{CC} = 3.3 \text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

^{\S} This is the increase in supply current for each input that is at the specified voltage level, rather than V_{CC} or GND.

^{\parallel} Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.



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switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	
t _{pd} [†]	A or B	B or A	0.15		0.25		ns
t _{en}	OE	A or B	1.6	4.5	1.9	4.2	ns
t _{dis}	OE	A or B	1.3	4.7	1	4.8	ns

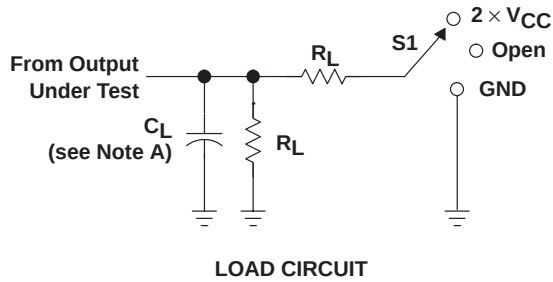
[†] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

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LOW-VOLTAGE QUADRUPLE FET BUS SWITCH

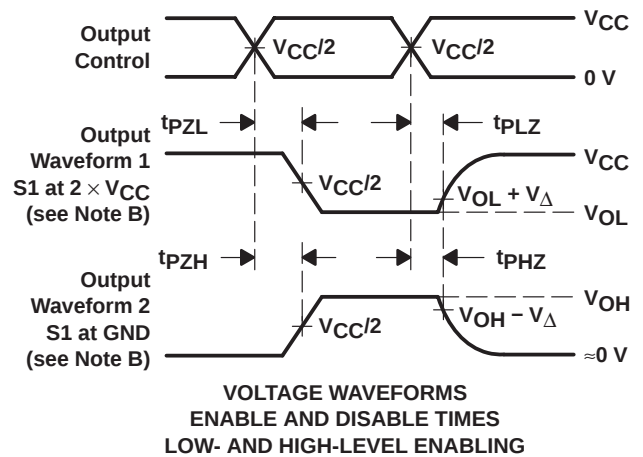
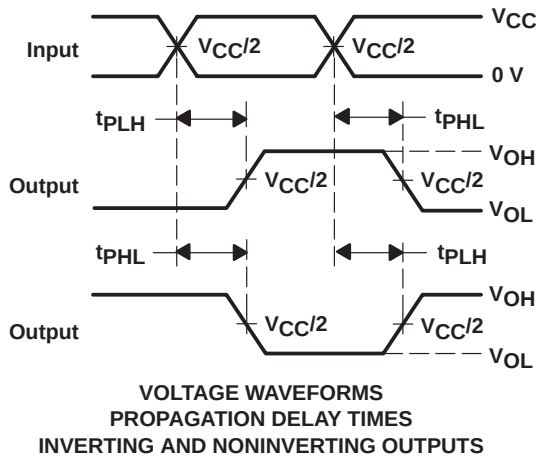
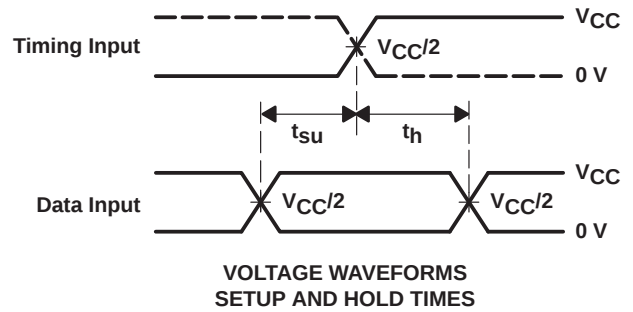
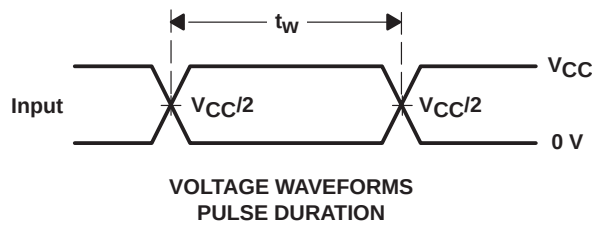
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PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	$2 \times V_{CC}$
t_{PHZ}/t_{PZH}	GND

V_{CC}	C_L	R_L	V_{Δ}
2.5 V $\pm$ 0.2 V	30 pF	500 Ω	0.15 V
3.3 V $\pm$ 0.3 V	50 pF	500 Ω	0.3 V



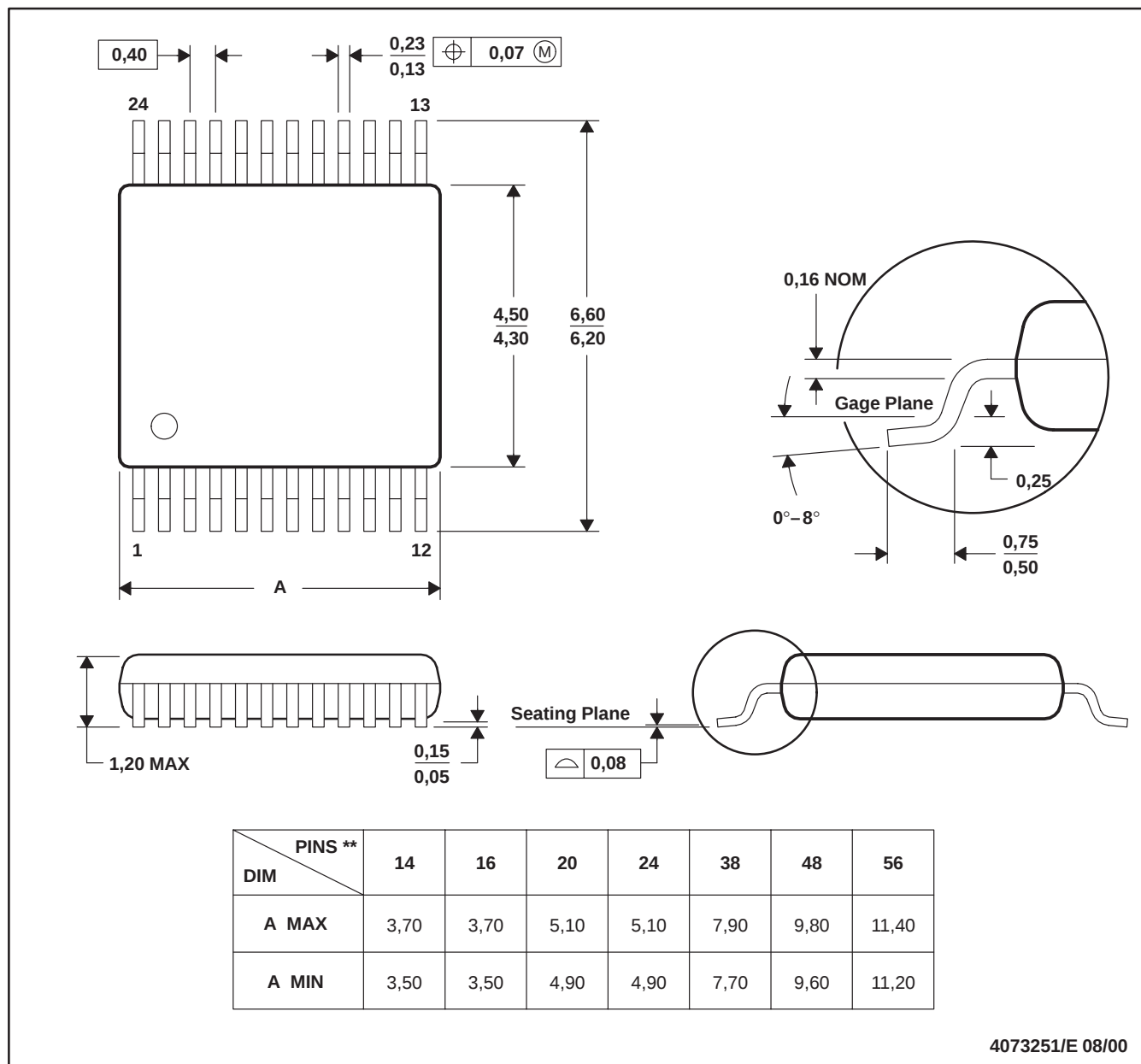
- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $t_r \leq 2$ ns, $t_f \leq 2$ ns.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .
 - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

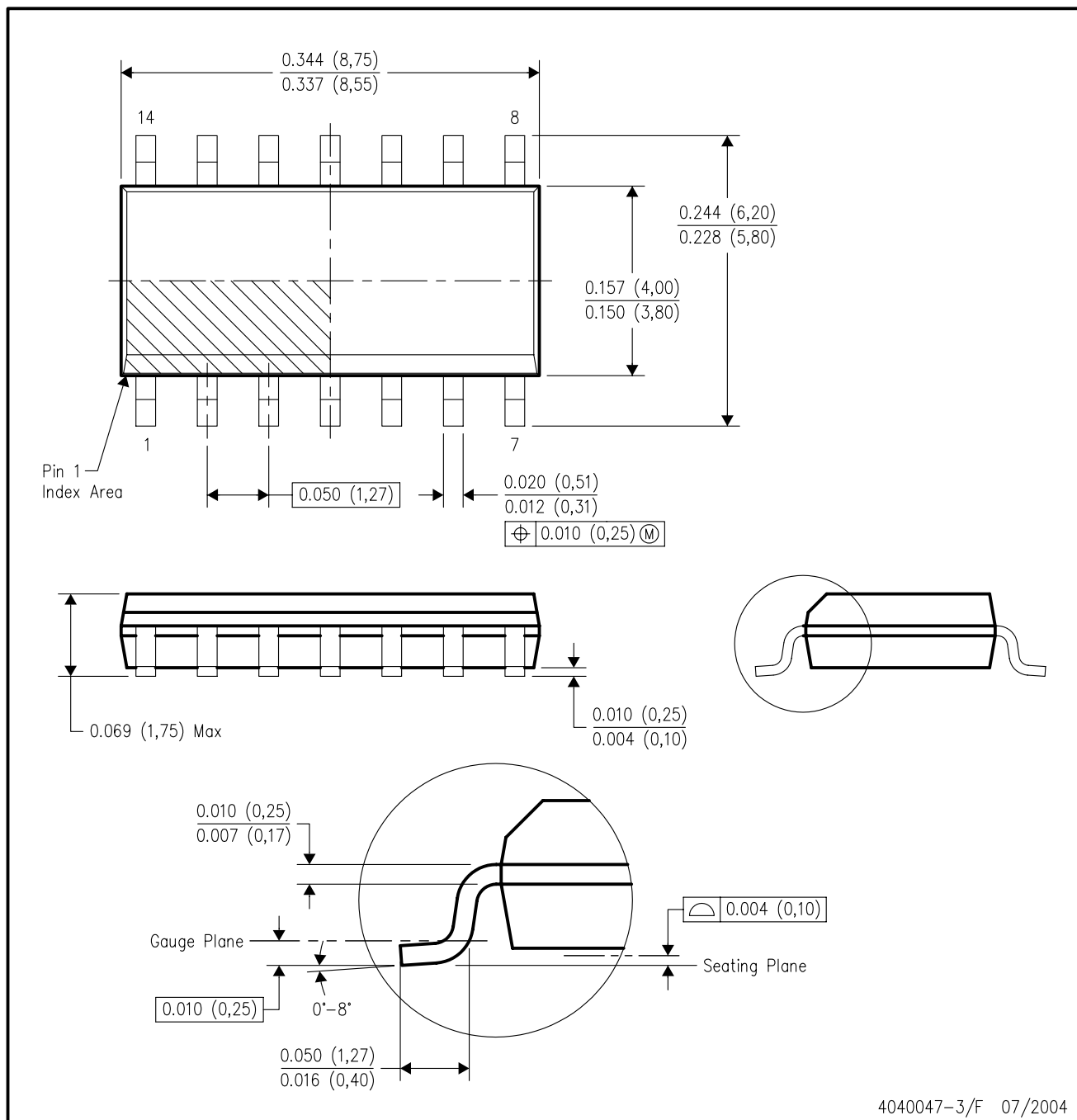
24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



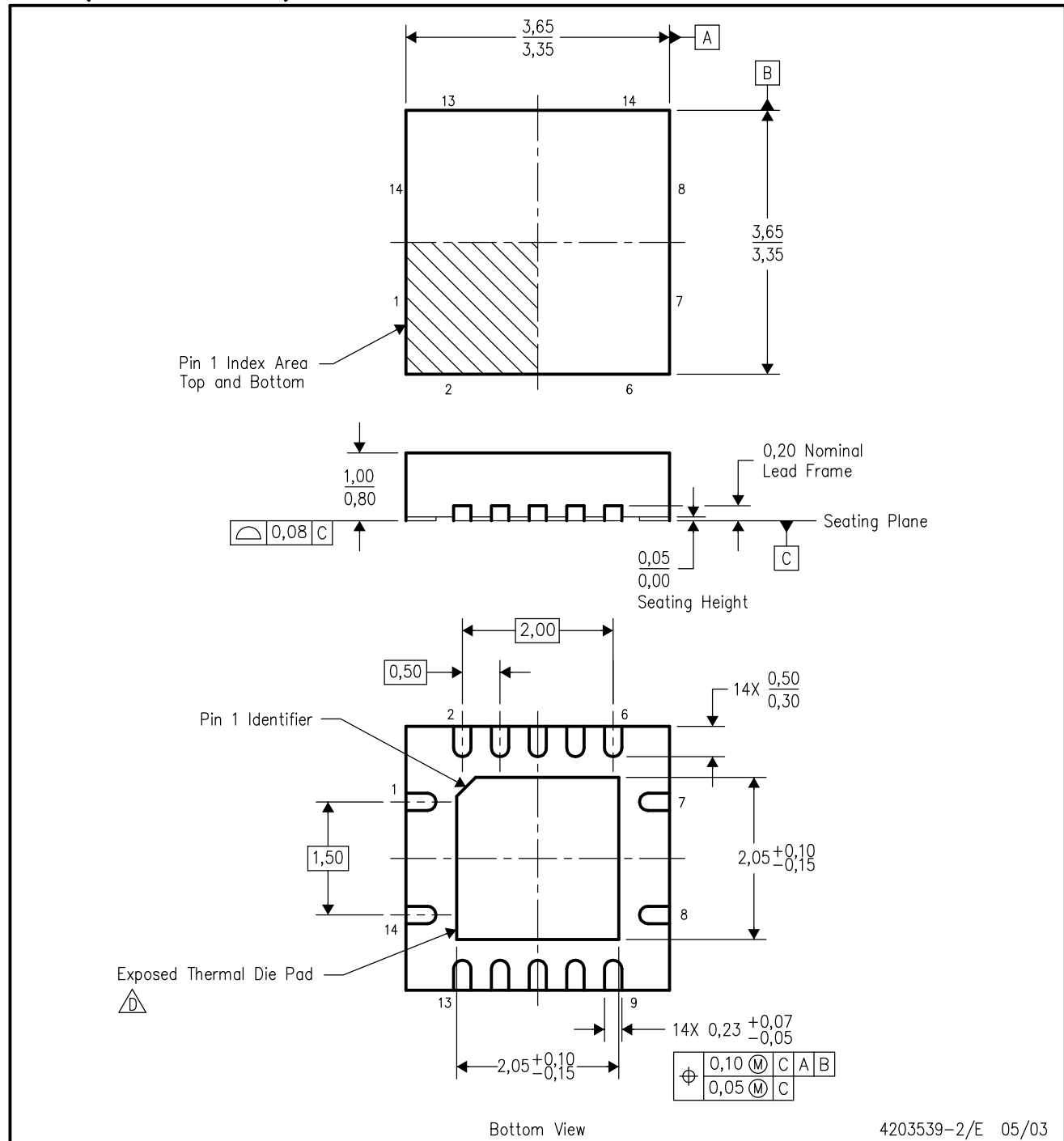
4040047-3/F 07/2004

NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- Falls within JEDEC MS-012 variation AB.

RGY (S-PQFP-N14)

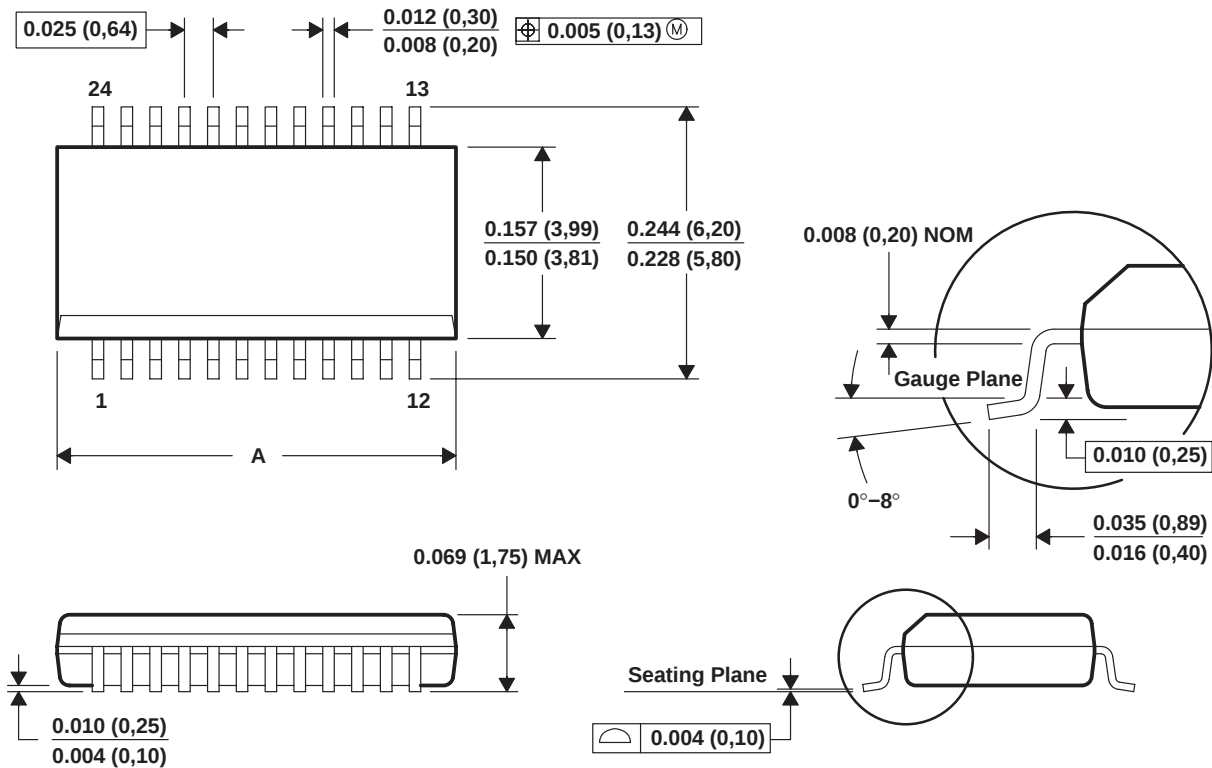
PLASTIC QUAD FLATPACK



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.
 - The package thermal performance may be enhanced by bonding the thermal die pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected ground leads.
 - E. Package complies to JEDEC MO-241 variation BA.

DBQ (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE



PINS **	16	20	24	28
DIM				
A MAX	0.197 (5,00)	0.344 (8,74)	0.344 (8,74)	0.394 (10,01)
A MIN	0.189 (4,80)	0.337 (8,56)	0.337 (8,56)	0.386 (9,80)
M0-137 VARIATION	AB	AD	AE	AF

4073301/F 02/2002

- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MO-137.

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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